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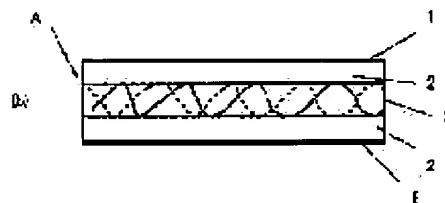
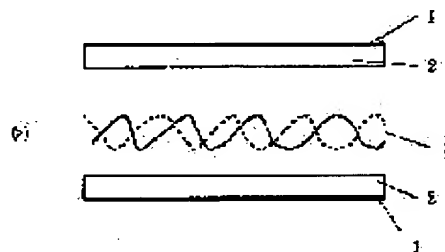
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(54) ORGANIC FIBER REINFORCED PRINTED WIRING BOARD AND MANUFACTURE THEREOF**(57)Abstract:**

PROBLEM TO BE SOLVED: To provide a light weight and thin film organic fiber reinforced printed wiring board without using an epoxy resin impregnated prepreg on the conventional glass fiber cloth, and to provide the manufacturing method of the board which can be formed efficiently at a high yield.

SOLUTION: This printed wiring board consists of metal foil sheets 1, the thermosetting resin 2 coating one surface of the metal foil sheet, and the woven or non-woven fabric reinforcement material 3 coating the other surface of the metal foil as shown in the figure (a). The reinforcement material 3 is pinched by the resin 2, the metal foil sheet 1 is adhered by molding under pressure and heat by positioning them outside, and an organic fiber reinforced double-side substrate 8 is formed as shown in the figure (b).

**LEGAL STATUS**

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